

FQS4900

Dual N & P-Channel, Logic Level MOSFET

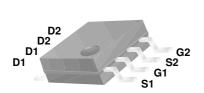
General Description

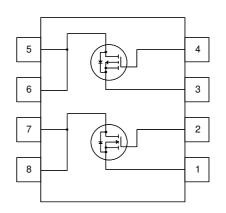
These dual N and P-channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. This device is well suited for high interface in telephone sets.

Features

- N-Channel 1.3A, 60V, $R_{DS(on)}$ = 0.55 Ω @ V_{GS} = 10 V $\begin{array}{c} \text{R}_{DS(on)} = 0.65~\Omega \quad @ \text{V}_{GS} = 5~\text{V} \\ \text{P-Channel -0.3A, -300V, R}_{DS(on)} = 15.5~\Omega @ \text{V}_{GS} = -10~\text{V} \\ \text{R}_{DS(on)} = 16~\Omega \quad @ \text{V}_{GS} = -5~\text{V} \\ \end{array}$ • Low gate charge (typical N-Channel 1.6 nC)
- (typical P-Channel 3.6 nC)
- · Fast switching
- Improved dv/dt capability





Absolute Maximum Ratings T_A = 25°C unless otherwise noted

Symbol	Parameter		N-Channel	P-Channel	Units
V _{DSS}	Drain-Source Voltage		60	-300	٧
I _D	Drain Current - Continuous (T _A = 25°C)		1.3	-0.3	Α
	- Continuous (T _A = 70°C))	0.82	-0.19	Α
I _{DM}	Drain Curent - Pulsed	(Note 1)	5.2	-1.2	Α
V _{GSS}	Gate-Source Voltage		± 20		V
dv/dt	Peak Diode Recovery dv/dt	(Note 2)	7.0	4.5	V/ns
P _D	Power Dissipation (T _A = 25°C)		2.0		W
	$(T_A = 70^{\circ}C)$		1.3		W
T_J , T_{STG}	Operating and Storage Temperature Range		-55 to	+150	°C

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62.5	°C/W

Symbol	Parameter	Test Conditions	Type	Min	Тур	Max	Units
Off Cha	aracteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	N-Ch	60			V
		$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	P-Ch	-300			٧
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 60 V, V _{GS} = 0 V				1	μА
טטי		V _{DS} = 48 V, T _C = 55°C	N-Ch			10	μA
		V _{DS} = -300 V, V _{GS} = 0 V	5.01			-1	μΑ
		V _{DS} = -240 V, T _C = 55°C	P-Ch			-10	μA
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 20 V, V _{DS} = 0 V	All			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -20 V, V _{DS} = 0 V	All			-100	nA
On Oha							ı
V _{GS(th)}	aracteristics Gate Threshold Voltage	$V_{DS} = 4V, I_{D} = 20 \text{ mA}$	N-Ch	1.0		1.95	V
· GS(III)	date Threshold Voltage	$V_{DS} = 4V, I_{D} = -20 \text{ mA}$	P-Ch	-1.0		-1.95	V
R _{DS(on)}	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}, I_D = 0.65 \text{ A}$			0.39	0.55	Ω
D3(0H)		$V_{GS} = 5 \text{ V}, I_D = 0.65 \text{ A}$	N-Ch		0.46	0.65	Ω
		V _{GS} = -10 V, I _D = -0.15 A			11.2	15.5	Ω
		$V_{GS} = -5 \text{ V}, I_D = -0.15 \text{ A}$	P-CH		11.4	16	Ω
9FS	Forward Transconductance	V _{DS} = 10 V, I _D = 0.65 A	N-CH		1.7		S
915	Torward Transconductance	$V_{DS} = -10 \text{ V}, I_{D} = -0.15 \text{ A}$	P-CH		0.6		S
Switchi	ing Characteristics						
t _{d(on)}	Turn-On Delay Time	N-Channel	N-Ch		5.7	21	ns
	Turn-On Delay Time	$V_{DD} = 30 \text{ V}, I_{D} = 1.3 \text{ A},$	P-Ch		10	30	ns
t _r	Turn-On Rise Time	$R_G = 25 \Omega$	N-Ch		21	50	ns
		D. Ohannad	P-Ch		25	60	ns
t _{d(off)} Turn-Off Delay Time		P-Channel $V_{DD} = -150 \text{ V}, I_{D} = -0.3 \text{ A},$	N-Ch		11	32	ns
+.	·	$R_G = 25 \Omega$	P-Ch N-Ch		35 17	80 45	ns
t _f	Turn-Off Fall Time	11G - 20 32	P-Ch		47	105	ns ns
Q _q	Total Gate Charge	N-Channel	N-Ch		1.6	2.1	nC
g	Total Gato Gharge	$V_{DS} = 48 \text{ V}, I_D = 1.3 \text{ A},$	P-Ch		3.6	4.7	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 5 V	N-Ch		0.28		nC
9-		P-Channel	P-Ch		0.42	-	nC
Q _{gd}	Gate-Drain Charge	$V_{DS} = -240 \text{ V}, I_{D} = -0.3 \text{ A},$	N-Ch		0.82	-	nC
		$V_{GS} = -5 V$	P-Ch		2.1		nC
Drain-S	Source Diode Characteristics a	nd Maximum Ratings					
I _S	Maximum Continuous Drain-Source Did		N-Ch			1.3	Α
-			P-Ch			-0.3	Α
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 1.3 \text{ A}$	N-Ch			1.5	V
		$V_{GS} = 0 \text{ V}, I_{S} = -0.3 \text{ A}$	P-Ch			-4.0	V

- Notes: 1. Repetitive Rating : Pulse width limited by maximum junction temperature 3. Pulse Test : Pulse width $\leq 300\mu s$, Duty cycle $\leq 2\%$ 4. Essentially independent of operating temperature

Typical Characteristics: N-Channel

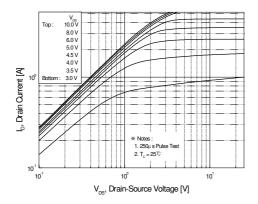


Figure 1. On-Region Characteristics

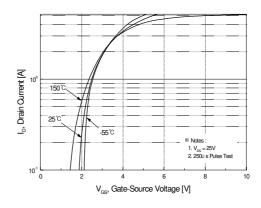


Figure 2. Transfer Characteristics

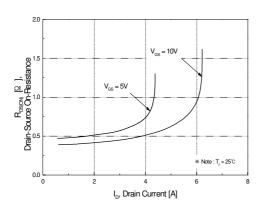


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

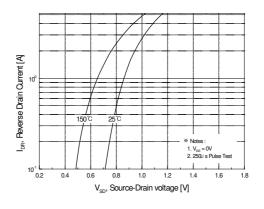


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

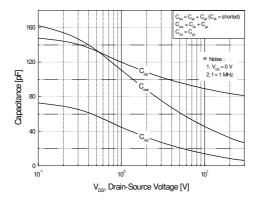


Figure 5. Capacitance Characteristics

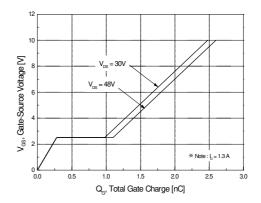


Figure 6. Gate Charge Characteristics

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Typical Characteristics: N-Channel (Continued)

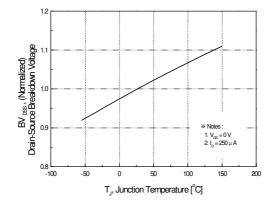
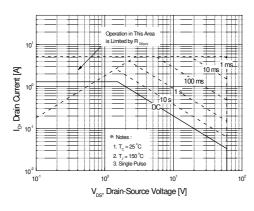


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



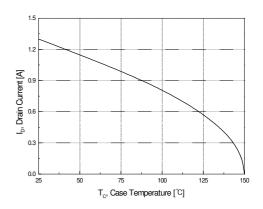


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

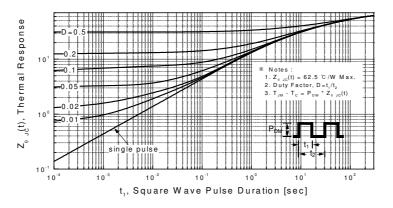


Figure 11. Transient Thermal Response Curve

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Typical Characteristics: P-Channel (Continued)

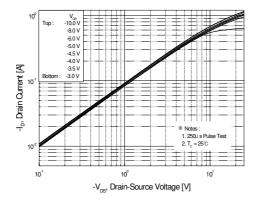


Figure 1. On-Region Characteristics

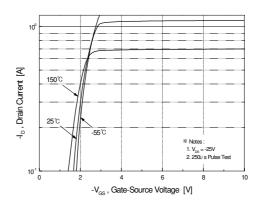


Figure 2. Transfer Characteristics

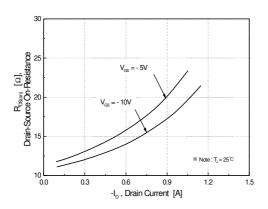


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

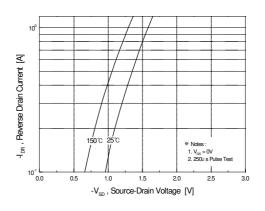


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

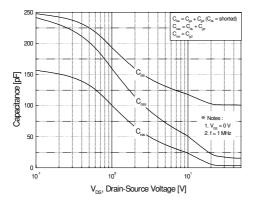


Figure 5. Capacitance Characteristics

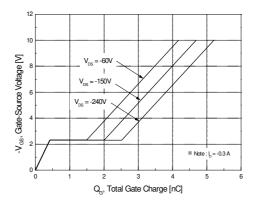


Figure 6. Gate Charge Characteristics

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Typical Characteristics: P-Channel (Continued)

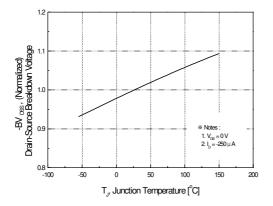
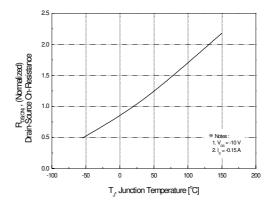


Figure 7. Breakdown Voltage Variation vs. Temperature Figure 8. On-Resistance Variation vs. Temperature



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Figure 9. Maximum Safe Operating Area

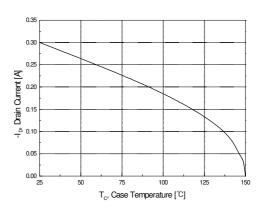


Figure 10. Maximum Drain Current vs. Case Temperature

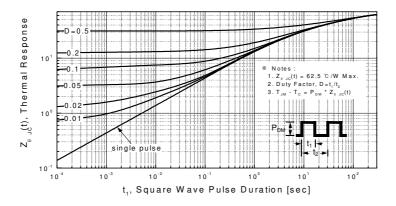
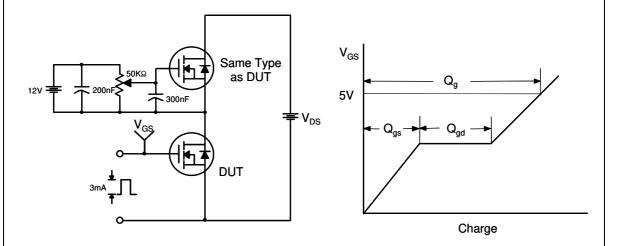


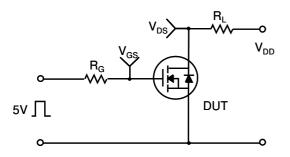
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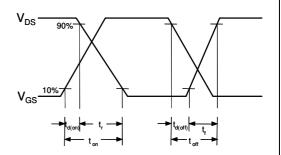
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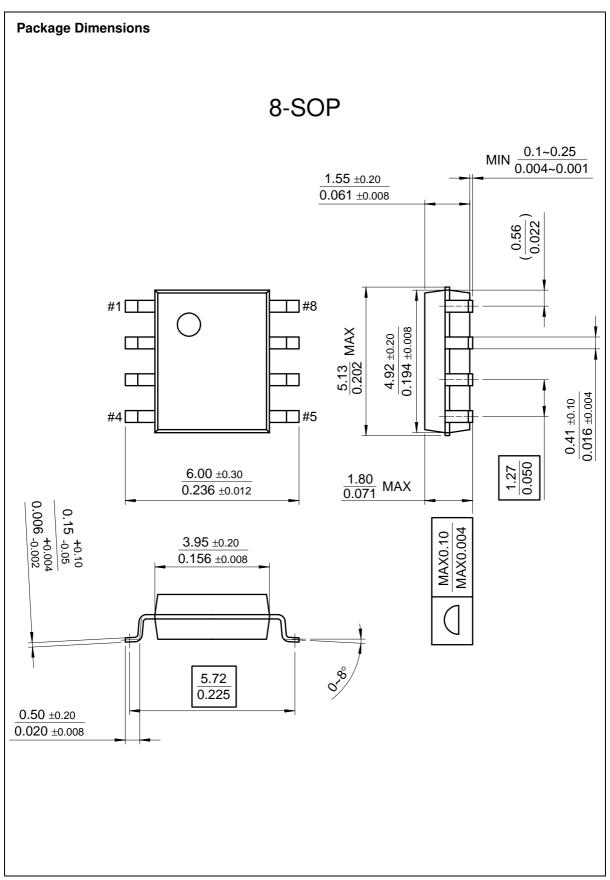
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms







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result in significant injury to the user.

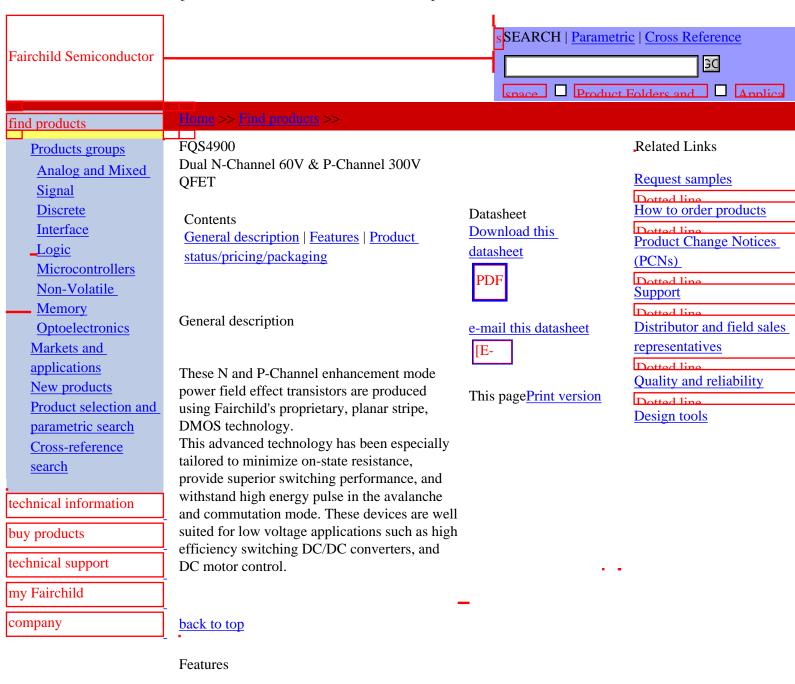
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 - $R_{DS(on)} = 0.65\Omega @ V_{GS} = 5 V$
- P-Channel -0.3A, -300V, $R_{DS(on)} = 15.5\Omega @ V GS = -10 V$
 - $R_{DS(on)} = 16 \Omega @ V_{GS} = -5 V$
- Low gate charge (typical N-Channel 1.6 nC) (typical P- Channel 3.6nC)
- Fast switching
- Improved dv/dt capability

Product status/pricing/packaging

Product	Product status	Pricing*	Package type	Leads	Packing method
FQS4900TF	Full Production	\$0.46	SOIC	8	TAPE REEL

^{* 1,000} piece Budgetary Pricing

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